

General Description

The AGM408MN combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM408MN	AGM408MN	SOP8	330mm	12mm	3000

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	40	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Ta=25°C) (Note 1)	11	A
	Drain Current-Continuous(Ta=100°C)	5	A
IDM (pulse)	Drain Current-Pulsed (Note 2)	44	A
PD	Maximum Power Dissipation(Ta=25°C)	2.5	w
	Maximum Power Dissipation(Ta=100°C)	1.0	w
EAS	Avalanche energy (Note 3)	64	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹	---	50	°C/W

Product Summary

BVDSS	RDSON	ID
40V	8.5mΩ	11A

SOP8 Pin Configuration

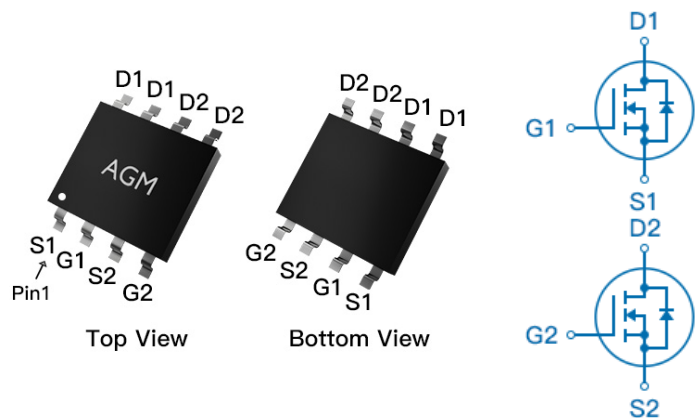


Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	40	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=40V,VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2	1.7	2.2	V
gFS	Forward Transconductance	VDS=5V,ID=5A	--	5.2	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=10A	--	8.5	11	mΩ
		VGS=4.5V, ID=5A	--	16	20	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=20V,VGS=0V, F=1MHZ	--	870	--	pF
Coss	Output Capacitance		--	265	--	pF
Crss	Reverse Transfer Capacitance		--	20	--	pF
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V,VDS=20V, ID=10A,REGEN=6Ω	--	5.6	--	nS
tr	Turn-on Rise Time		--	29	--	nS
td(off)	Turn-Off Delay Time		--	15	--	nS
tf	Turn-Off Fall Time		--	4.6	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=20V, ID=10A	--	13	--	nC
Qgs	Gate-Source Charge		--	2.7	--	nC
Qgd	Gate-Drain Charge		--	1.6	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	11	A
VSD	Forward on Voltage	VGS=0V,IS=10A	--	0.8	1.2	V
trr	Reverse Recovery Time	IF=10A , dI/dt=100A/μs , TJ=25℃	--	--	--	ns
Qrr	Reverse Recovery Charge		--	--	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C, VDD=25V, Vgs=10V, ID=16A, L=0.5mH, RG=25ohm

Typical Characteristics

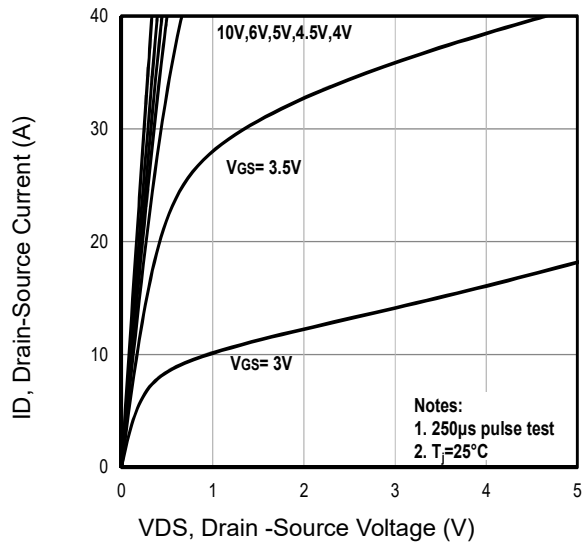


Fig1. Typical Output Characteristics

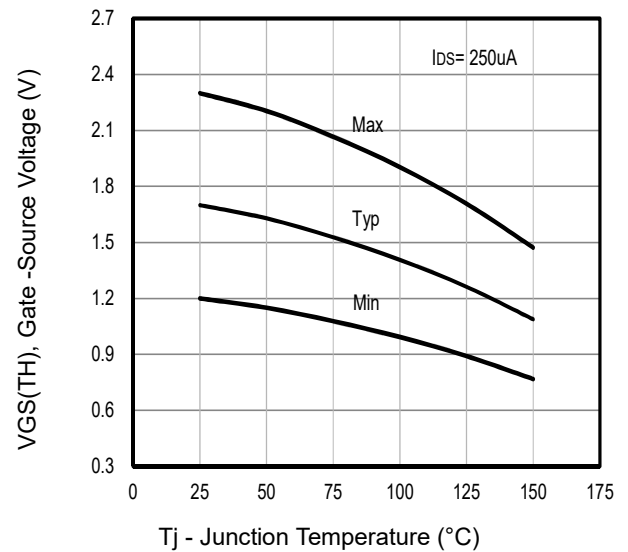


Fig2. Typical $V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

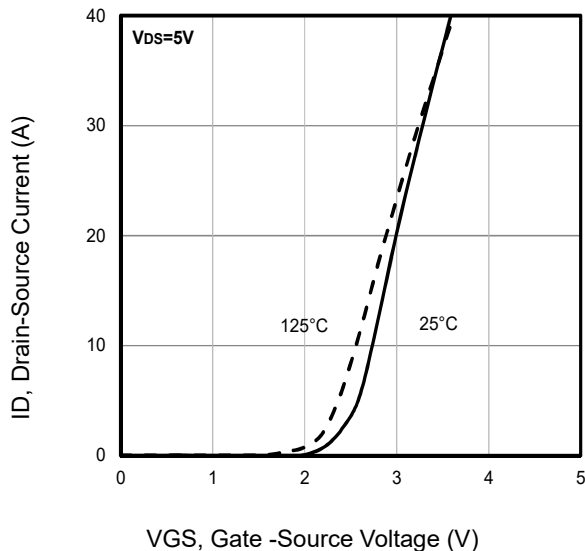


Fig3. Typical Transfer Characteristics

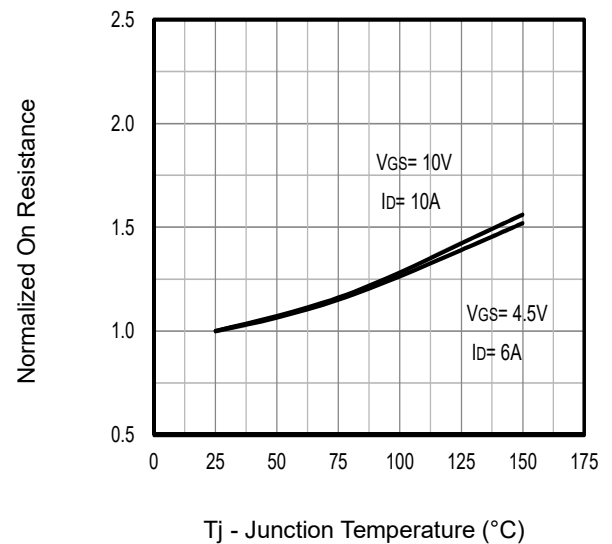


Fig4. Typical Normalized On-Resistance Vs. T_j

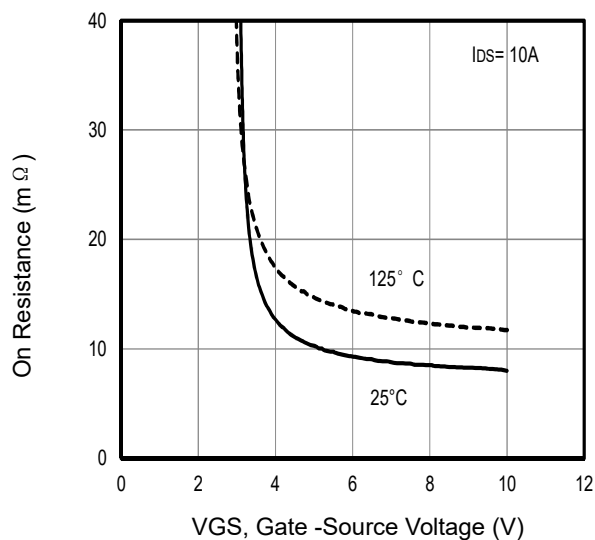


Fig5. Typical On Resistance Vs Gate-Source Voltage

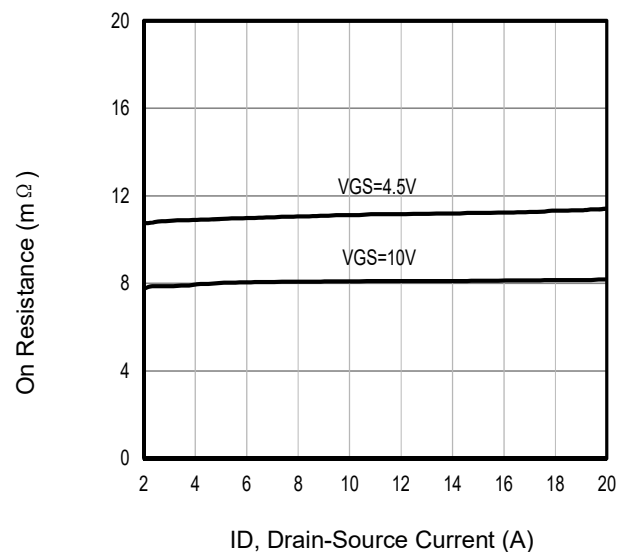


Fig6. Typical On Resistance Vs Drain Current

Typical Characteristics

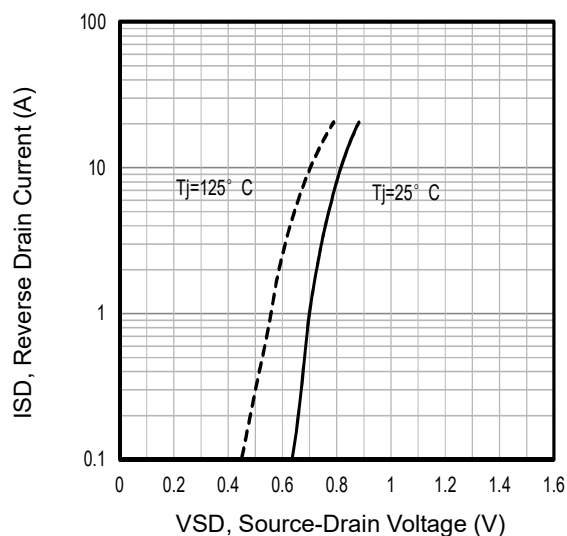


Fig7. Typical Source-Drain Diode Forward Voltage

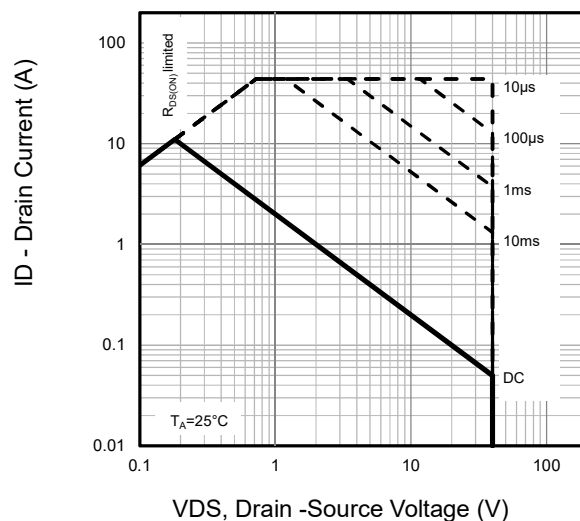


Fig8. Maximum Safe Operating Area

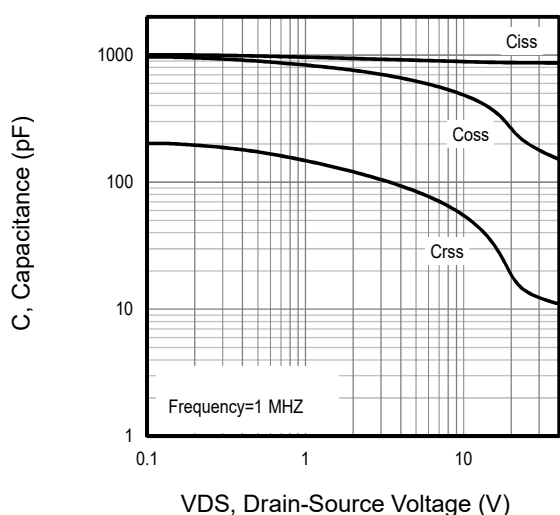


Fig9. Typical Capacitance Vs. Drain-Source Voltage

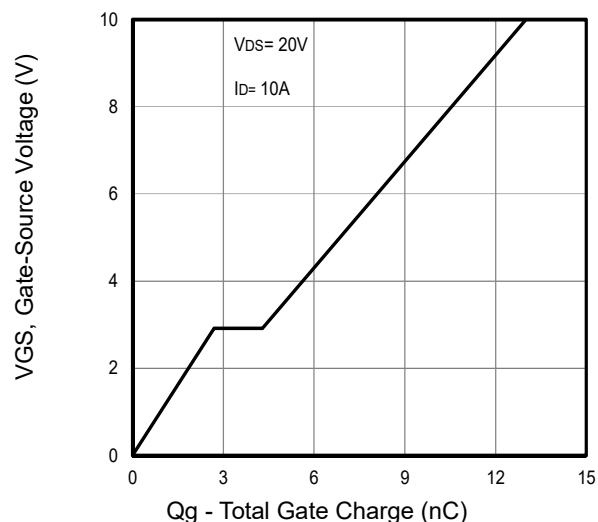


Fig10. Typical Gate Charge Vs. Gate-Source Voltage

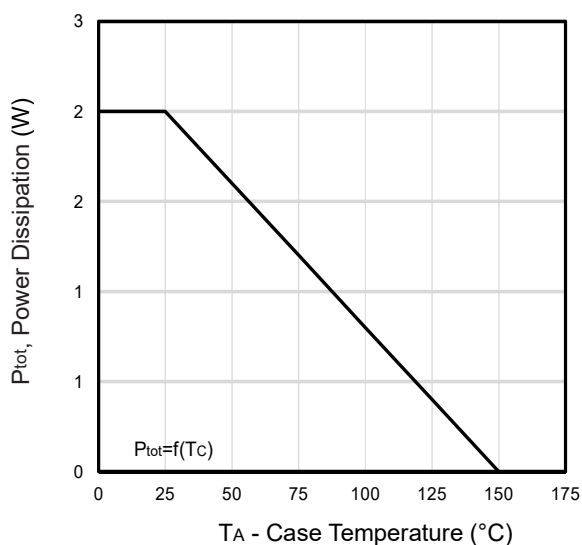


Fig11. Power Dissipation Vs. Case Temperature

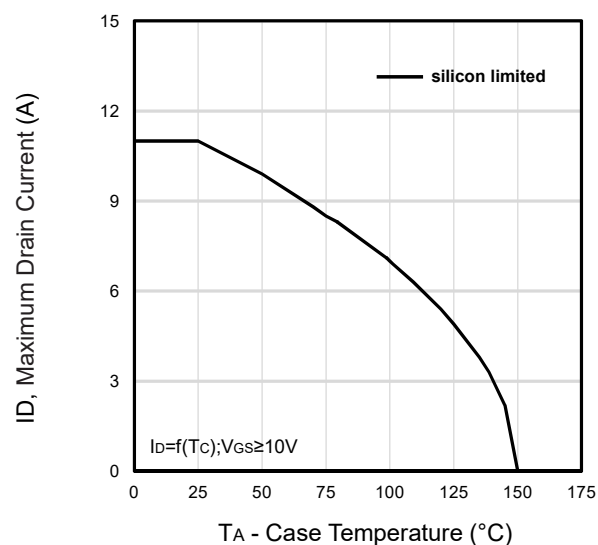


Fig12. Maximum Drain Current Vs. Case Temperature

Typical Characteristics

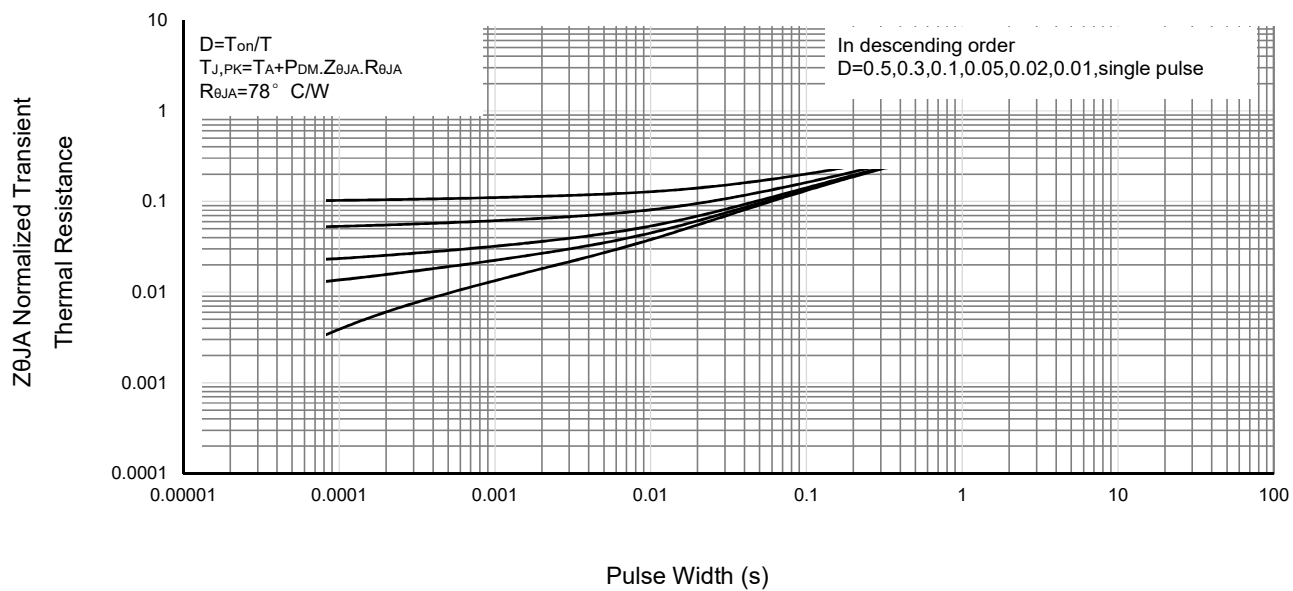
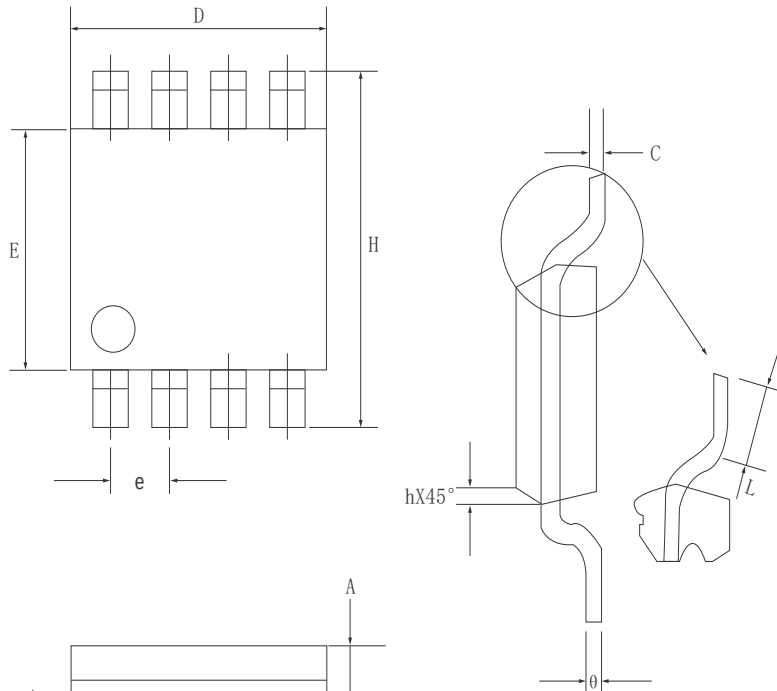
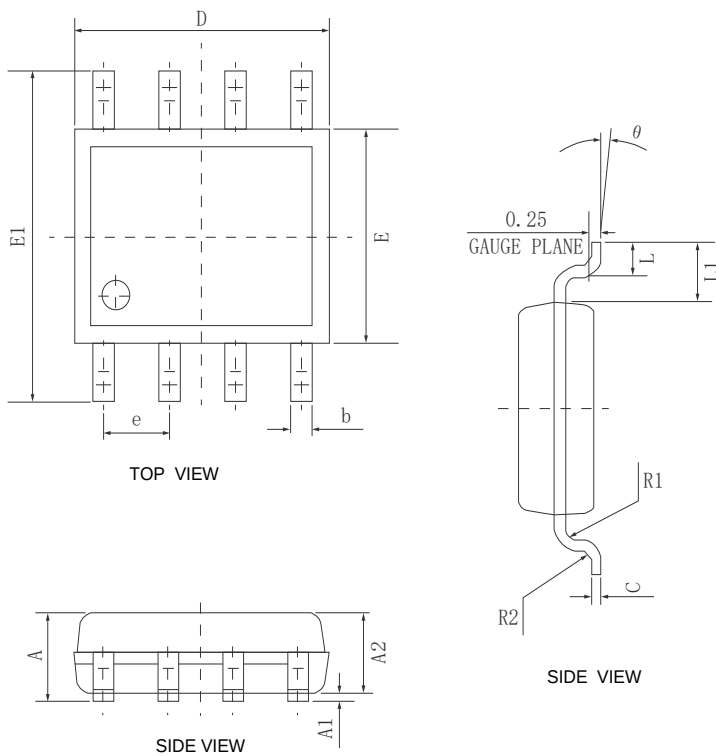


Fig13 . Normalized Maximum Transient Thermal Impedance

Dimensions (SOP8)



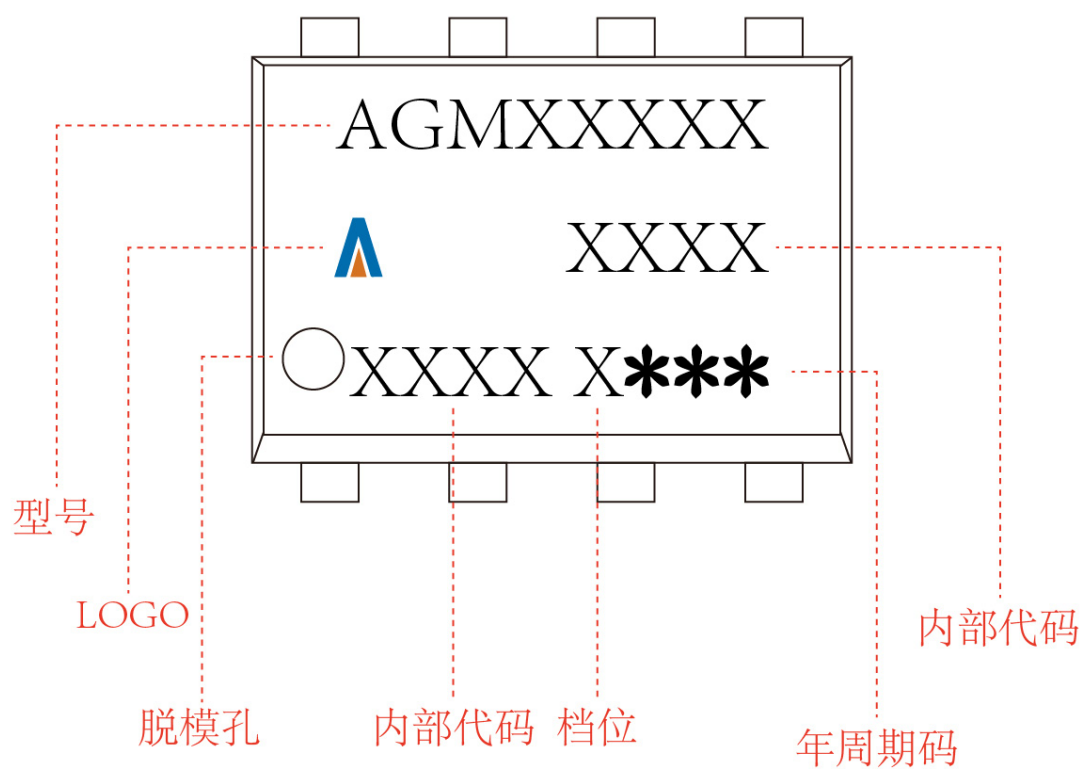
DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.02	0.15
B	0.33	0.5
C	0.1	0.25
D	4.8	5
E	3.8	4
e	1.27 (BSC)	
H	5.8	6.2
h	0.25	0.5
I	0.4	1.25
θ	0°	7°



SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
θ	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		

SOP8

Marking Instructions:



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